CT DELSS1.12

FIREFLY® E1608

The FIREFLY E1608 family expands OSRAM Opto Semiconductors' portfolio of visible products for use in mobile devices like fitness tracking or health monitoring.
It offers one of the smallest LED footprints in a highly reliable and proven package. The compact size of only 0.8 mm x 1.6 mm x 0.6 mm allows customers the benefit of more flexible product designs. The true green CT DELSS1.22 is specially designed for Heart Rate Monitor applications.

Applications

- Health Monitoring (Heart Rate Monitoring, Pulse Oximetry)

Features:

- Package: white SMT package, colorless clear resin
- Chip technology: UX:3
- Typ. Radiation: 120° (Lambertian emitter)
- Color: λ_{dom} = 530 nm (● true green)
- Corrosion Robustness Class: 1B
- ESD: 2 kV acc. to ANSI/ESDA/JEDEC JS-001 (HBM, Class 2)

Ordering Information

Type	Luminous Intensity [1] I_F = 20 mA I_v	Ordering Code
CT DELSS1.12-AABB-36-N626	1120 ... 2800 mcd	Q65113A0021

Maximum Ratings

Parameter	Symbol		Values
Operating Temperature	T_{op}	min. max.	-40 °C 85 °C
Storage Temperature	T_{stg}	min. max.	-40 °C 85 °C
Junction Temperature	T_j	max.	90 °C
Forward current T_S = 25 °C	I_F	min. max.	3 mA 30 mA
Surge Current t ≤ 10 µs; D = 0.005 ; T_S = 25 °C	I_{FS}	max.	70 mA
Reverse voltage [2] T_S = 25 °C	V_R	max.	5 V
ESD withstand voltage acc. to ANSI/ESDA/JEDEC JS-001 (HBM, Class 2)	V_{ESD}		2 kV

Characteristics

I_F = 20 mA; T_S = 25 °C

Parameter	Symbol		Values
Peak Wavelength	λ_{peak}	typ.	525 nm
Dominant Wavelength [3] I_F = 20 mA	λ_{dom}	min. typ. max.	519 nm 530 nm 543 nm
Viewing angle at 50% I_V	2φ	typ.	120 °
Forward Voltage [4] I_F = 20 mA	V_F	min. typ. max.	2.2 V 2.6 V 3.1 V
Reverse current [2] V_R = 5 V	I_R	typ. max.	0.01 µA 10 µA
Real thermal resistance junction/ambient [5][6]	$R_{thJA\ real}$	typ. max.	420 K / W 580 K / W
Real thermal resistance junction/solderpoint [5]	$R_{thJS\ real}$	typ. max.	51 K / W 68 K / W

Brightness Groups

Group	Luminous Intensity [1] I_F = 20 mA min. I_v	Luminous Intensity. [1] I_F = 20 mA max. I_v	Luminous Flux [7] I_F = 20 mA typ. Φ_V
AA	1120 mcd	1400 mcd	3960 mlm
AB	1400 mcd	1800 mcd	5020 mlm
BA	1800 mcd	2240 mcd	6340 mlm
BB	2240 mcd	2800 mcd	7910 mlm

Forward Voltage Groups

Group	Forward Voltage [4] I_F = 20 mA min. V_F	Forward Voltage [4] I_F = 20 mA max. V_F
N6	2.2 V	2.5 V
U6	2.5 V	2.8 V
26	2.8 V	3.1 V

Wavelength Groups

Group	Dominant Wavelength [3] I_F = 20 mA min. λ_{dom}	Dominant Wavelength [3] I_F = 20 mA max. λ_{dom}
3	519 nm	525 nm
4	525 nm	531 nm
5	531 nm	537 nm
6	537 nm	543 nm

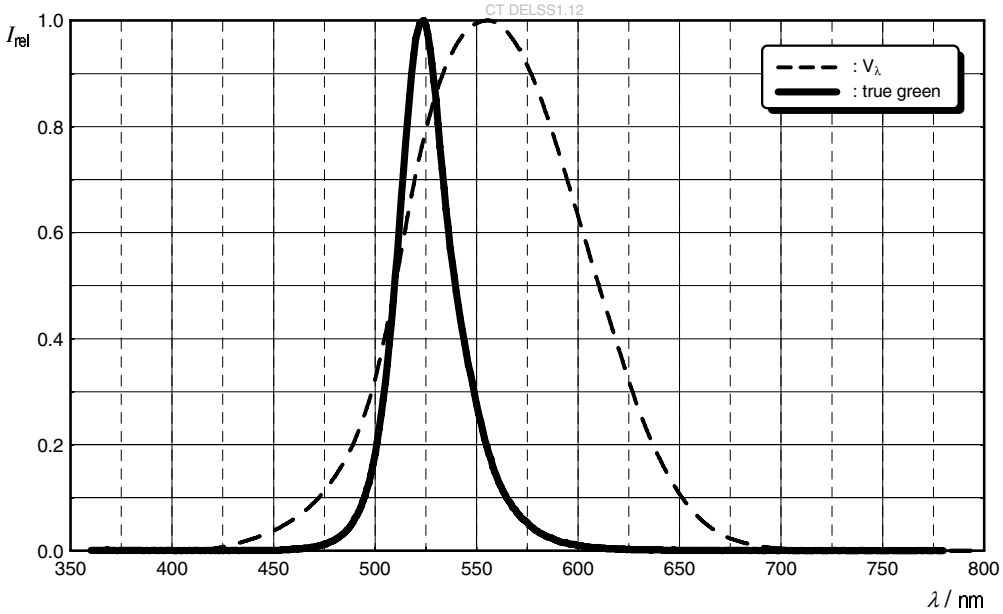
Group Name on Label

Example: AA-3-26

Brightness	Wavelength	Forward Voltage
AA	3	26

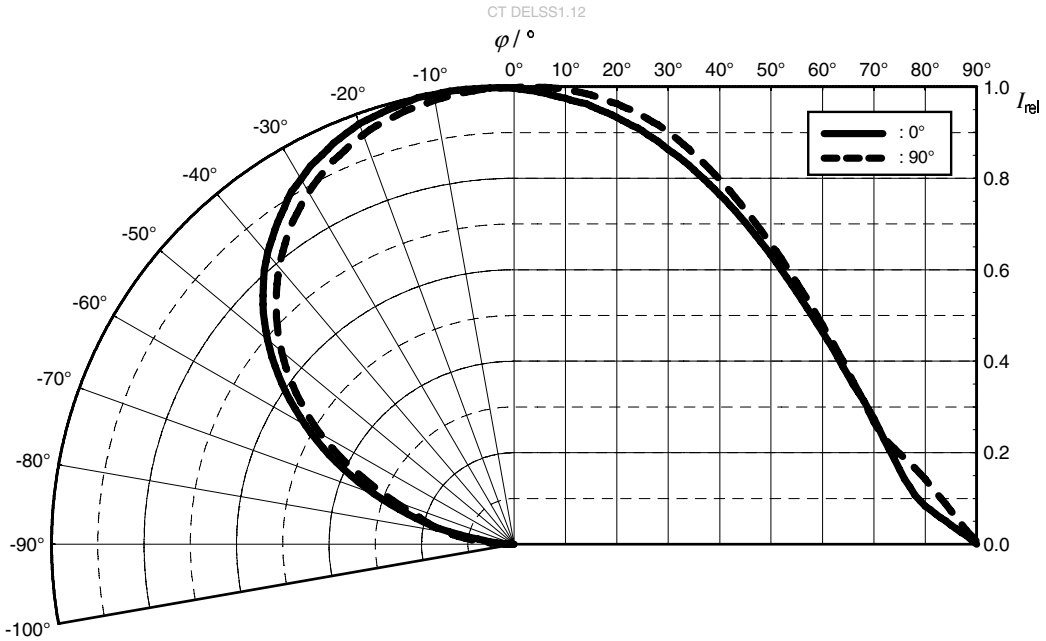
Relative Spectral Emission [7)]

$I_{rel} = f(\lambda)$; $I_F = 20$ mA; $T_S = 25$ °C



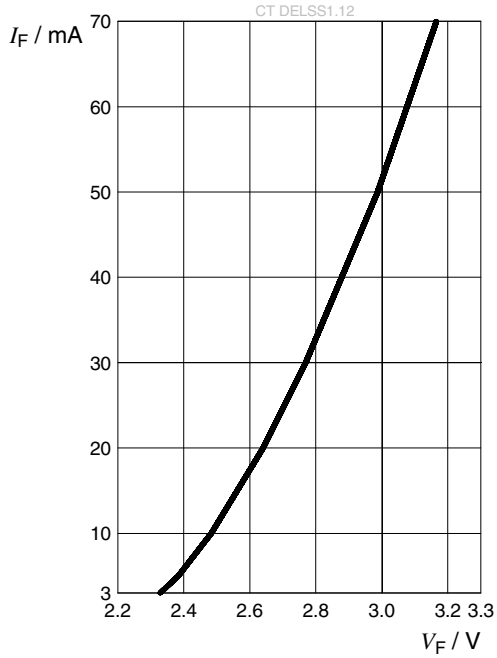
Radiation Characteristics [7)]

$I_{rel} = f(\phi)$; $T_S = 25$ °C



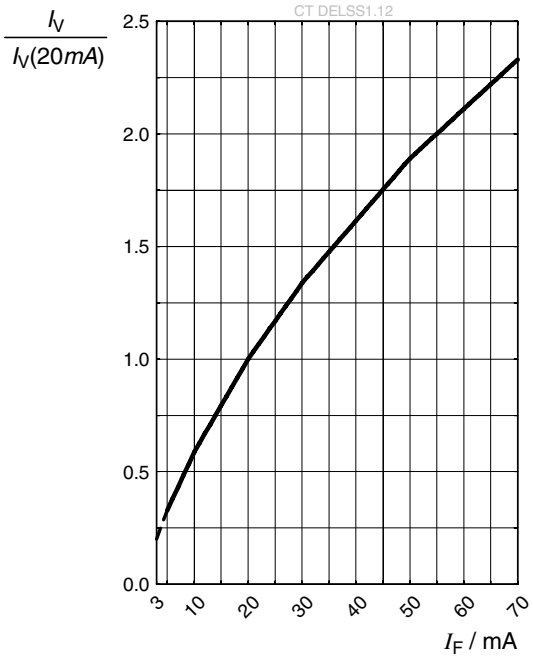
Forward current [7)]

$I_F = f(V_F)$; T_S = 25 °C



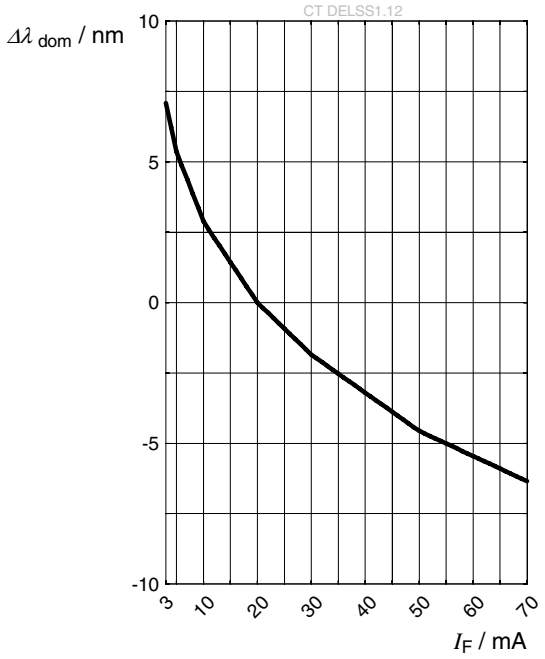
Relative Luminous Intensity [7), 8)]

$I_v/I_v(20\ mA) = f(I_F)$; T_S = 25 °C



Dominant Wavelength [7)]

$\Delta\lambda_{dom} = f(I_F)$; T_S = 25 °C



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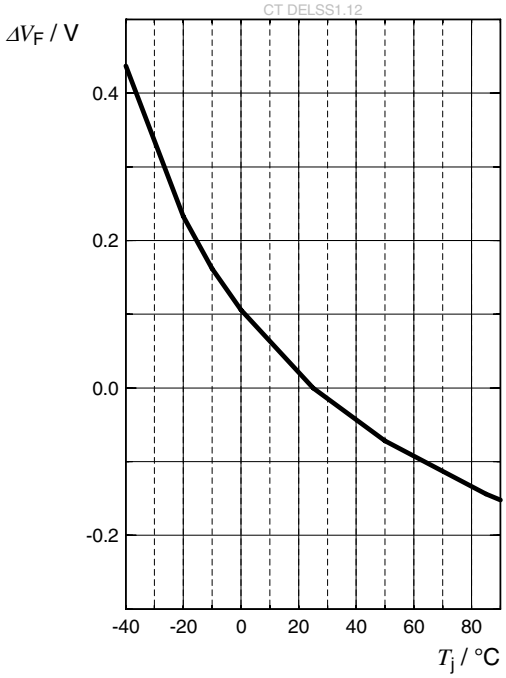
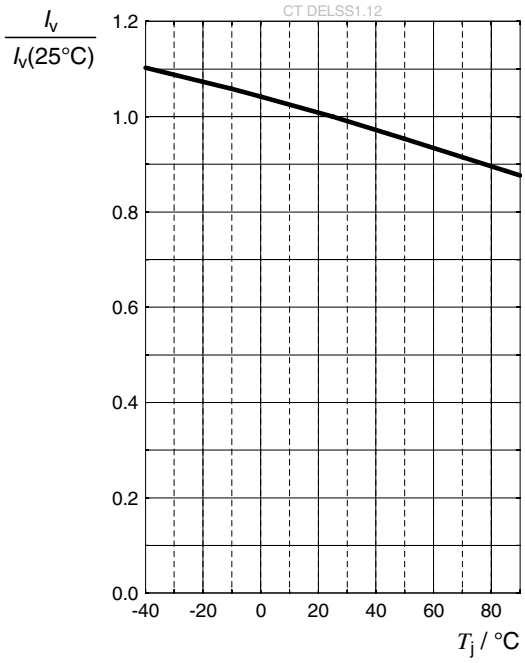
Forward Voltage [7)]

$\Delta V_F = V_F - V_F(25\ °C) = f(T_j);\ I_F = 20\ mA$



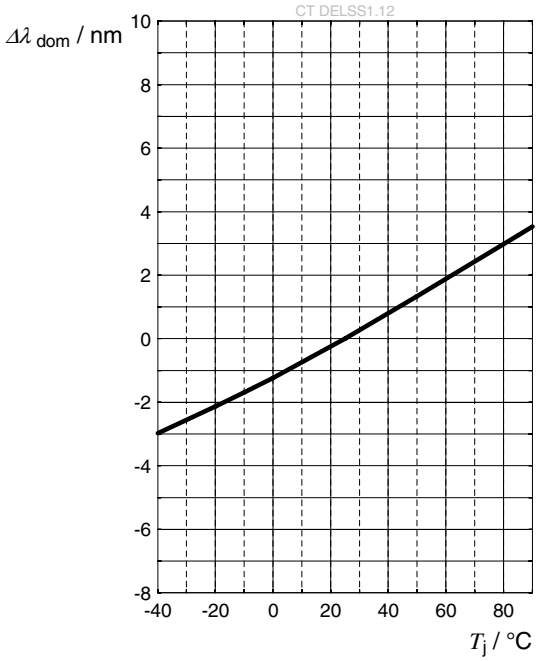
Relative Luminous Intensity [7)]

$I_v/I_v(25\ °C) = f(T_j);\ I_F = 20\ mA$



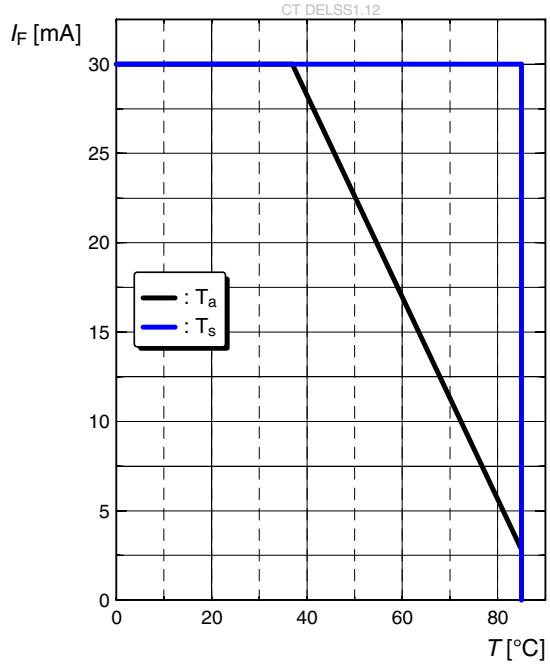
Dominant Wavelength [7)]

$\Delta\lambda_{dom} = \lambda_{dom} - \lambda_{dom}(25\ °C) = f(T_j);\ I_F = 20\ mA$



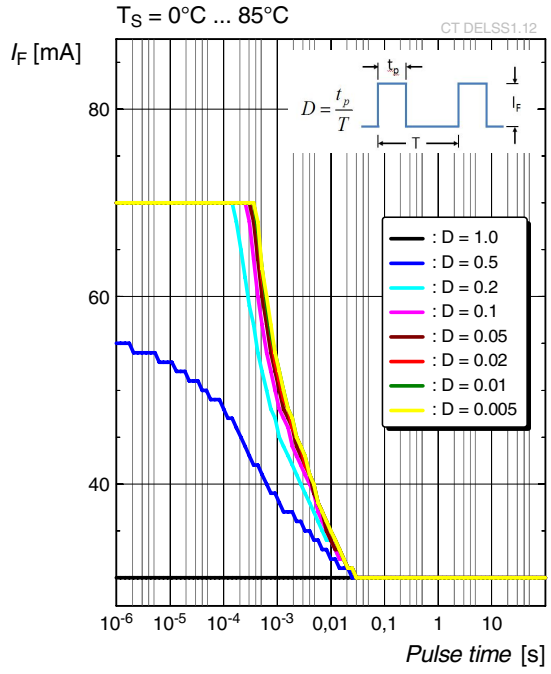
Max. Permissible Forward Current

$I_F = f(T)$

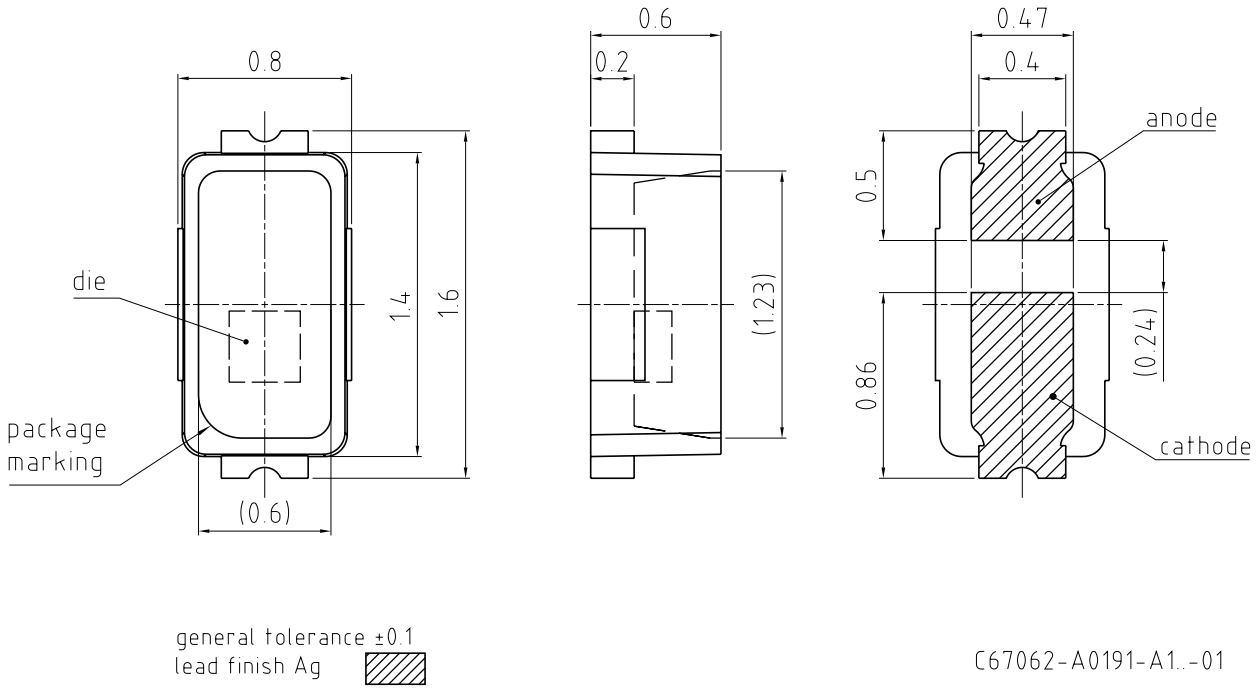


Permissible Pulse Handling Capability

$I_F = f(t_p)$; D: Duty cycle



Dimensional Drawing [9)]



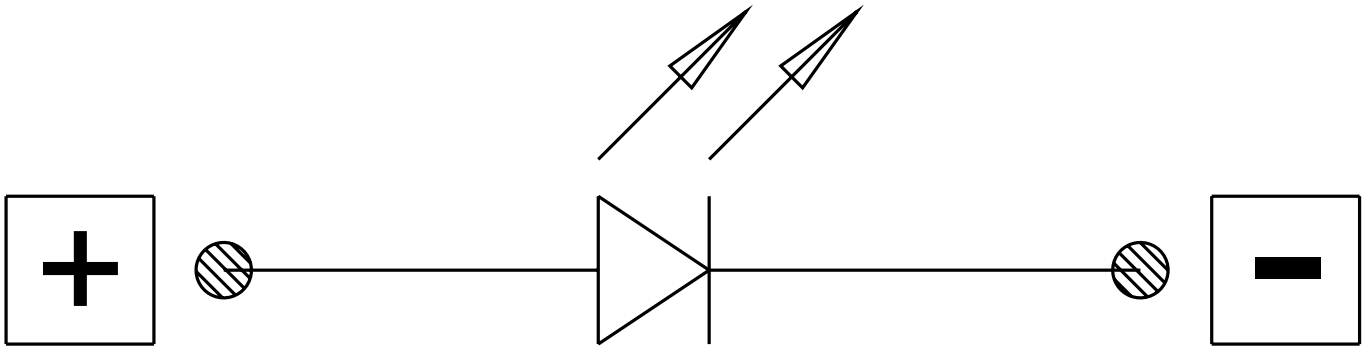
Further Information:

Approximate Weight: 2.0 mg

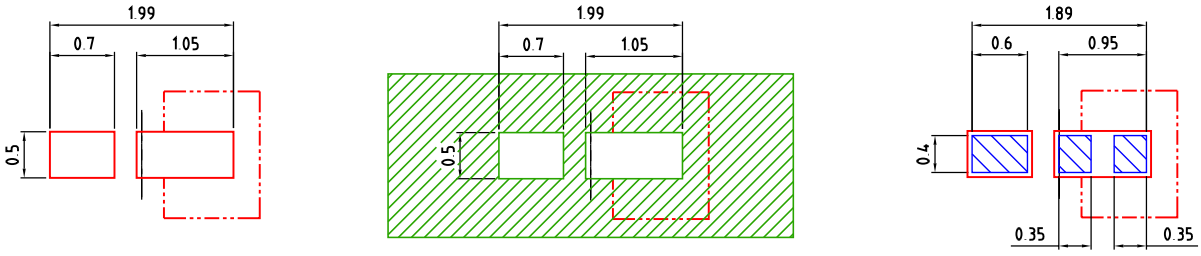
Package marking: Cathode

Corrosion test: Class: 1B
Test condition: 25°C / 75 % RH / 200ppb SO_2, 200ppb NO_2, 10ppb H_2S, 10ppb Cl_2 / 21 days (EN 60068-2-60 (Method 4))

Electrical Internal Circuit



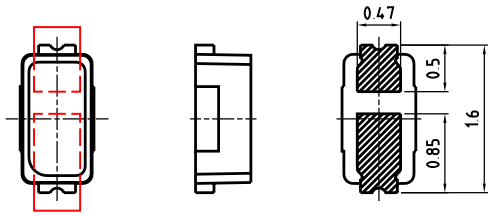
Recommended Solder Pad [9)]



foot print Cu area solder resist solder stencil

The usage of solder resist between anode and cathode pads is mandatory for applications where water may condense

Component Location on Pad



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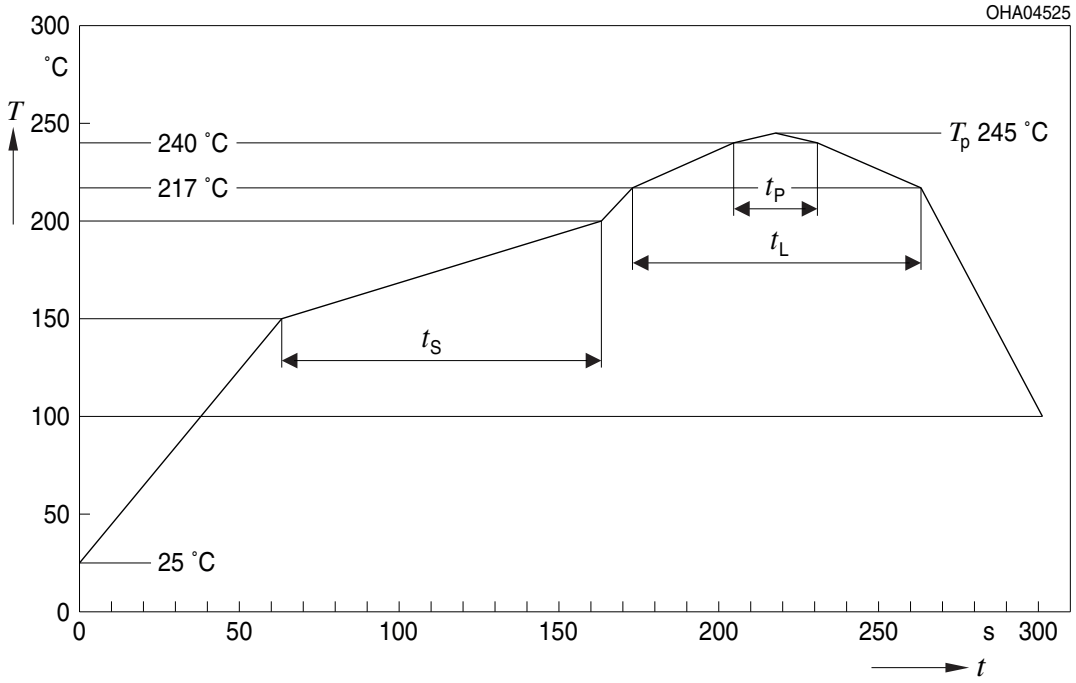
For superior solder joint connectivity results we recommend soldering under standard nitrogen atmosphere.

Reflow Soldering Profile

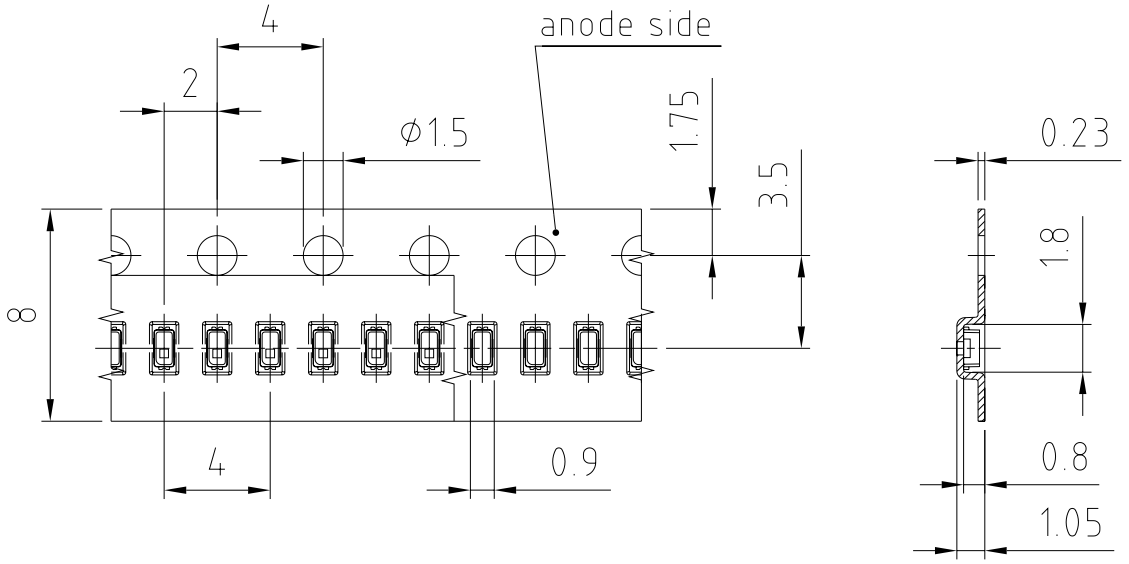
Product complies to MSL Level 3 acc. to JEDEC J-STD-020E



Profile Feature	Symbol	Pb-Free (SnAgCu) Assembly			Unit
		Minimum	Recommendation	Maximum	
Ramp-up rate to preheat*) 25 °C to 150 °C			2	3	K/s
Time t_S T_{Smin} to T_{Smax}	t_S	60	100	120	s
Ramp-up rate to peak*) T_{Smax} to T_P			2	3	K/s
Liquidus temperature	T_L		217		°C
Time above liquidus temperature	t_L		80	100	s
Peak temperature	T_P		245	260	°C
Time within 5 °C of the specified peak temperature T_P - 5 K	t_P	10	20	30	s
Ramp-down rate* T_P to 100 °C			3	6	K/s
Time 25 °C to T_P				480	s

All temperatures refer to the center of the package, measured on the top of the component
* slope calculation DT/Dt: Dt max. 5 s; fulfillment for the whole T-range

Taping [9)]



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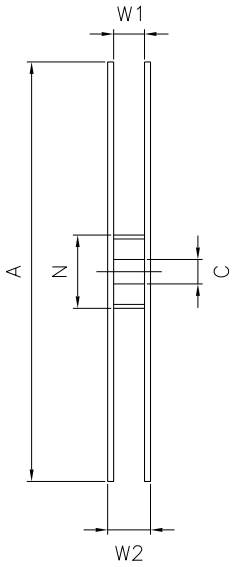
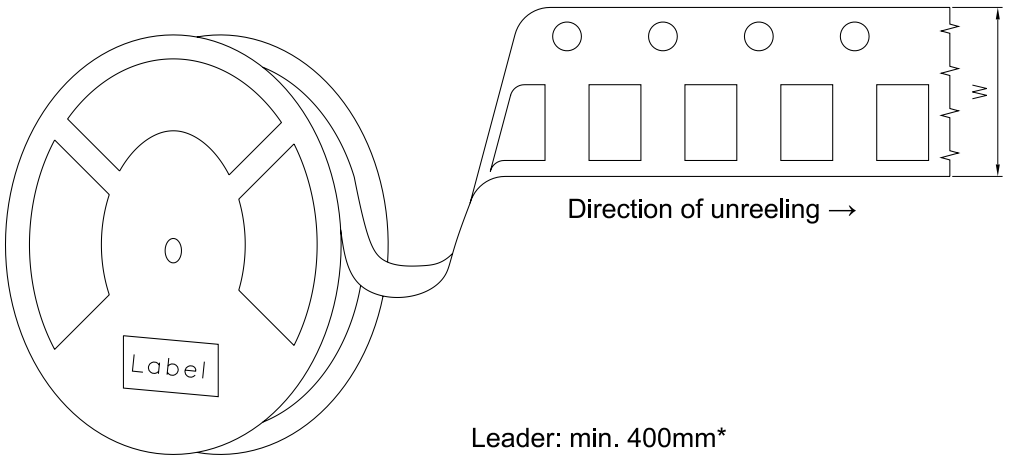
Tape and Reel [10)]



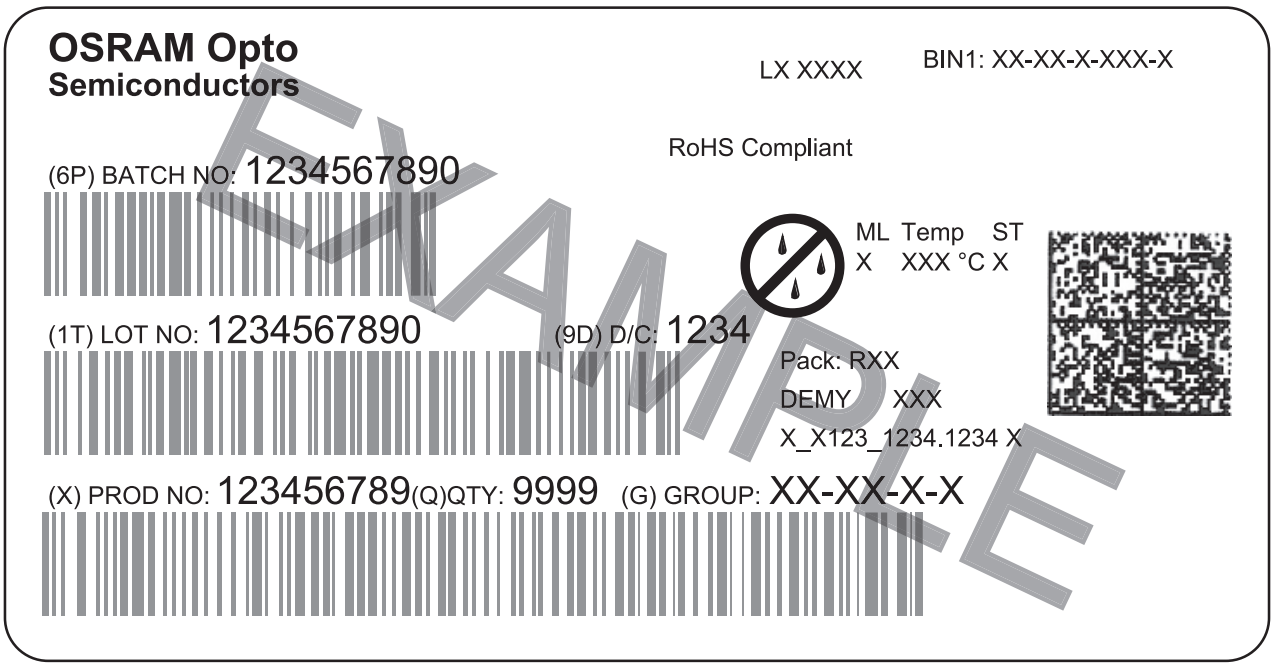


Leader: min. 400mm*
Trailer: min. 160mm*
*)Dimensions acc. to IEC 60286-3; EIA 481-E

Reel Dimensions

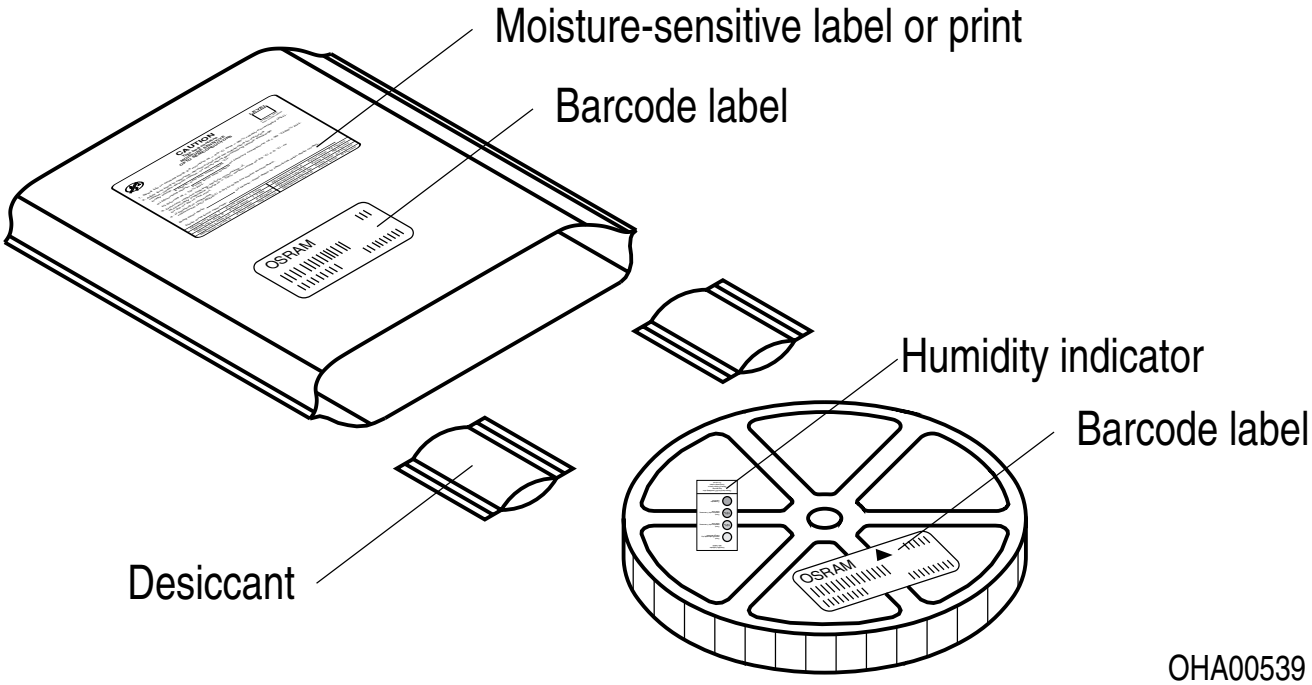
A	W	N_{min}	W_1	$W_{2\,max}$	Pieces per PU
180 mm	8 + 0.3 / - 0.1 mm	60 mm	8.4 + 2 mm	14.4 mm	9000

Barcode-Product-Label (BPL)



OHA04563

Dry Packing Process and Materials [9)]



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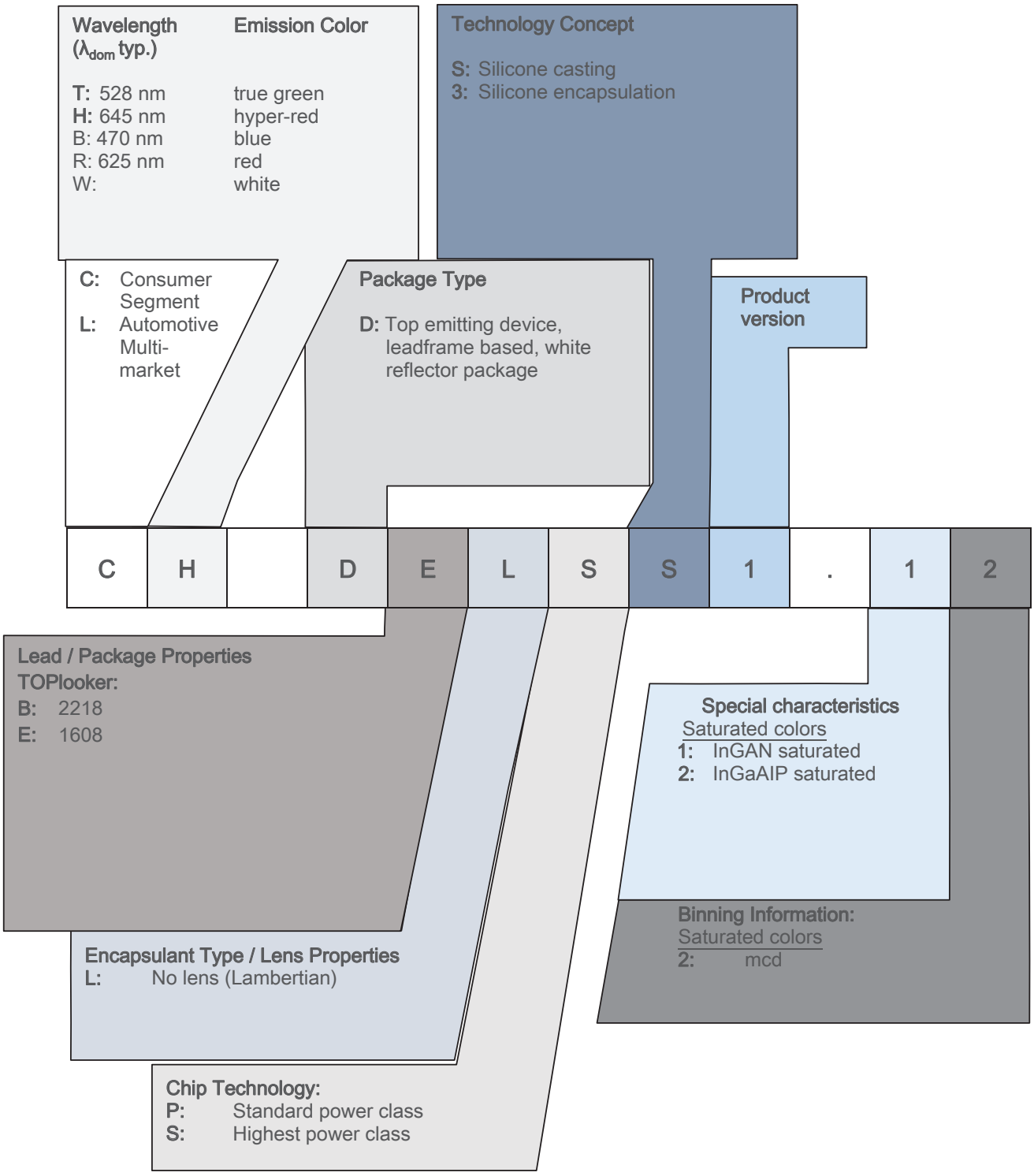
Moisture-sensitive product is packed in a dry bag containing desiccant and a humidity card according JEDEC-STD-033.

Type Designation System



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Notes

The evaluation of eye safety occurs according to the standard IEC 62471:2006 (photo biological safety of lamps and lamp systems). Within the risk grouping system of this IEC standard, the device specified in this data sheet falls into the class **exempt group (exposure time 10000 s)**. Under real circumstances (for exposure time, conditions of the eye pupils, observation distance), it is assumed that no endangerment to the eye exists from these devices. As a matter of principle, however, it should be mentioned that intense light sources have a high secondary exposure potential due to their blinding effect. When looking at bright light sources (e.g. headlights), temporary reduction in visual acuity and afterimages can occur, leading to irritation, annoyance, visual impairment, and even accidents, depending on the situation.

Subcomponents of this device contain, in addition to other substances, metal filled materials including silver. Metal filled materials can be affected by environments that contain traces of aggressive substances. Therefore, we recommend that customers minimize device exposure to aggressive substances during storage, production, and use. Devices that showed visible discoloration when tested using the described tests above did show no performance deviations within failure limits during the stated test duration. Respective failure limits are described in the IEC60810.

For further application related information please visit www.osram-os.com/appnotes

Disclaimer

Attention please!
The information describes the type of component and shall not be considered as assured characteristics.
Terms of delivery and rights to change design reserved. Due to technical requirements components may contain dangerous substances.
For information on the types in question please contact our Sales Organization.
If printed or downloaded, please find the latest version on the OSRAM OS website.

Packing
Please use the recycling operators known to you. We can also help you – get in touch with your nearest sales office. By agreement we will take packing material back, if it is sorted. You must bear the costs of transport. For packing material that is returned to us unsorted or which we are not obliged to accept, we shall have to invoice you for any costs incurred.

Product and functional safety devices/applications or medical devices/applications
OSRAM OS components are not developed, constructed or tested for the application as safety relevant component or for the application in medical devices.
OSRAM OS products are not qualified at module and system level for such application.

In case buyer – or customer supplied by buyer – considers using OSRAM OS components in product safety devices/applications or medical devices/applications, buyer and/or customer has to inform the local sales partner of OSRAM OS immediately and OSRAM OS and buyer and /or customer will analyze and coordinate the customer-specific request between OSRAM OS and buyer and/or customer.

Glossary

1) **Brightness:** Brightness values are measured during a current pulse of typically 25 ms, with an internal reproducibility of ±8 % and an expanded uncertainty of ±11 % (acc. to GUM with a coverage factor of k = 3).

2) **Reverse Operation:** This product is intended to be operated applying a forward current within the specified range. Applying any continuous reverse bias or forward bias below the voltage range of light emission shall be avoided because it may cause migration which can change the electro-optical characteristics or damage the LED.

3) **Wavelength:** The wavelength is measured at a current pulse of typically 25 ms, with an internal reproducibility of ±0.5 nm and an expanded uncertainty of ±1 nm (acc. to GUM with a coverage factor of k = 3).

4) **Forward Voltage:** The forward voltage is measured during a current pulse of typically 8 ms, with an internal reproducibility of ±0.05 V and an expanded uncertainty of ±0.1 V (acc. to GUM with a coverage factor of k = 3).

5) **Thermal Resistance:** Rth max is based on statistic values (6σ).

6) **Thermal Resistance:** RthJA results from mounting on PC board FR 4 (pad size 16 mm² per pad)

7) **Typical Values:** Due to the special conditions of the manufacturing processes of semiconductor devices, the typical data or calculated correlations of technical parameters can only reflect statistical figures. These do not necessarily correspond to the actual parameters of each single product, which could differ from the typical data and calculated correlations or the typical characteristic line. If requested, e.g. because of technical improvements, these typ. data will be changed without any further notice.

8) **Characteristic curve:** In the range where the line of the graph is broken, you must expect higher differences between single devices within one packing unit.

9) **Tolerance of Measure:** Unless otherwise noted in drawing, tolerances are specified with ±0.1 and dimensions are specified in mm.

10) **Tape and Reel:** All dimensions and tolerances are specified acc. IEC 60286-3 and specified in mm.

Revision History

Version	Date	Change
1.4	2020-04-02	Ordering Information Characteristics Brightness Groups Electro - Optical Characteristics (Diagrams)
1.5	2020-05-14	Tape and Reel

Published by OSRAM Opto Semiconductors GmbH
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EU RoHS and China RoHS compliant product

此产品符合欧盟 RoHS 指令的要求；
按照中国的相关法规和标准，不含有毒有害物质或元素。